


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST25TV512C-AFF3	CBG9*TVIA0PA	A	994I	2021-04-05
	Amount	UoM	Unit type	ST ECOPACK Grade
	0.11	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
Not Applicable	Not Applicable	Not Applicable		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Not Applicable	N/A		

Package Designator	Size	Nbr of instances	Shape	
CHP	0.954x0.853x0.120	4	No lead	
Comment	Package : B01N 75UM GOLD BUMPED DICE DM00249510			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-19th January 2021				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	CBG9*TVIAOPA				2000001.0	999999.3
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	0.105	mg	supplier	die	Silicon (Si)	7440-21-3		0.090	mg	857143	800675
				supplier	metallization	Aluminium (Al)	7429-90-5		0.001	mg	9524	8896
				supplier	metallization	Copper (Cu)	7440-50-8		0.004	mg	38095	35586
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.001	mg	9524	8896
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	9524	8896
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	9524	8896
Bump	M-011 Other inorganic materials	0.007	mg	supplier	Passivation	Silicon Oxide	7631-86-9		0.007	mg	66667	62275
				supplier	Bump metallization	Gold (Au)	7440-57-5		0.007	mg	1000000	65879

